

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
DAISUKE KUGIMOTO	07/30/2021
KOKI KAMIYA	07/30/2021
SHINGO KOUDA	07/30/2021
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<b>Postal Code:</b>	7468501
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17401515
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<b>NAME OF SUBMITTER:</b>	HIROKO DERELLO
<b>SIGNATURE:</b>	/Hiroko Derello/
<b>DATE SIGNED:</b>	08/13/2021
<b>Total Attachments: 3</b>	
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# ASSIGNMENT WITH DECLARATION FOR PATENT APPLICATION (37 CFR 1.63)

## 特許出願宣言書付き譲渡書(37 CFR 1.63)

### Japanese Language Assignment with Declaration

下記に署名した発明者であり、以下に譲渡人と称される私（我々）は、下記の出願に記載された改良に関する発明をし、

\_\_\_\_\_ の \_\_\_\_\_（譲受人）は、本件出願および本件発明、ならびに当該出願から得られるいかなる米国特許に関する全ての権利、権原、および利益の取得を要求します。

よって、価値ある対価の受領をここに確認し、

上で譲渡人として指名された私（我々）は、米国における本件出願およびその発明開示、全ての分割出願および継続出願、これら出願について許可された米国特許証、全ての再発行特許、ならびに全ての外国出願に関する全ての権利（改正後のパリ条約（1883年）に基づく優先権、ならびに 35 USC 119 に基づき優先権を主張する権利と過去分の損害賠償請求権を含む）、権原、および利益を、上で指定した譲受人、その承継人ないし権利承継者に売却、譲渡、移転するとともに、私（我々）は米国特許商標庁長官に対し、本件出願に記載の発明に対する特許証を、譲受人、その承継人ないし権利承継者に発行することを要請し、また、私（我々）は、譲受人が本件発明に係る外国特許出願を行うことに同意し、これ以上の対価なしに、譲受人の求めにより、本件米国・外国特許出願に関して譲受人が必要とみなす全ての書類を作成します。

（公証人による認証は不要であるが、これらの書類は、35 USC 261 に基づく推定された証拠となる）

私は、下記に記載の発明者として、以下の通り宣言します。

本宣言付き譲渡書は、以下に関します。

- 添付の出願書、または、  
 \_\_\_\_\_年\_\_月\_\_日に 出願された米国出願あるいは PCT 国際出願番号 \_\_\_\_\_

本件出願の名称は、以下の通りです。

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Whereas, I/We, the undersigned inventor(s) hereinafter called assignor(s), have invented certain improvements described in the application identified below; and

Whereas, TOSOH CORPORATION of 4560, Kaisei-cho, Shunan-shi, Yamaguchi 7468501, Japan, (assignee), desires to acquire the entire right, title, and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

I/We, the above named assignor(s), hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including all divisions, and continuations thereof, and all Letters Patent of the United States that may be granted thereon, and all reissues thereof, and all countries foreign thereto, including rights of priority under the International Convention of Paris (1883) as amended, including the right to claim priority under 35 USC 119 and the right to sue for past damages, and I/we request the Director of the U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and I/we hereby agree that the assignee may apply for foreign Letters Patent on the invention and I/we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States and foreign applications when called upon to do so by the assignee.

(Legalization not required for recording but is prima facie evidence of execution under 35 USC 261)

As the below named inventor, I hereby declare that:

This assignment with declaration is directed to:

- The attached application, or  
 United States Application or PCT International Application Number \_\_\_\_\_ filed on \_\_\_\_\_

The application is entitled:

RESIN COMPOSITION, MODIFIER, AND RESIN  
COMPOSITION INCLUDING THE MODIFIER

Japanese Language Assignment with Declaration

上記に明示された出願は、私が作成した、または作成を許可したものです。

私は、本件出願において請求項に記載された発明の本発明の発明者、または、本来の共同発明者であると信じています。

私は、本宣誓付き譲渡書の提出に関わる本件出願の内容を検討し、理解しています。

私は、37 CFR 1.56 に定義されるように、自身を知る全ての特許性に関する重要な情報を、米園特許商標庁に開示する義務があることを認識しています。

私は、本宣誓付き譲渡書において故意に虚偽の供述を行った場合、18 USC 1001 に基づき、罰金あるいは5年以下の懲役、または両方による処罰の対象となることを認識しています。

The above identified application was made or was authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the application for which this assignment with declaration is being submitted.

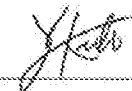
I am aware of the duty to disclose to the Office all information known to me to be material to patentability as defined in 37 CFR 1.56.

I hereby acknowledge that any willful false statement made in this assignment with declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

STATEMENT OF ACCURATE TRANSLATION IN ACCORDANCE WITH 37 CFR 1.69(b):

The assignment with declaration is an accurate translation of the corresponding English language assignment with declaration.

Signature



Date

March 11, 2014

NAME OF SOLE OR FIRST INVENTOR: 唯一あるいは第一の発明者名		
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Inventor's signature 発明者の署名	Koki Kamiya	Date 日付 July 30, 2021
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NAME OF THIRD INVENTOR: 第三の発明者名:		
Given Name (first and middle [if any]) 名 (名およびミドルネーム[該当する場合])	Shingo	Family Name or Surname 姓 KOUDA
Inventor's signature 発明者の署名	Shingo Kouda	Date 日付 July 30, 2021
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